



BASIC MECHANISMS INVOLVED IN FAST SINTERING

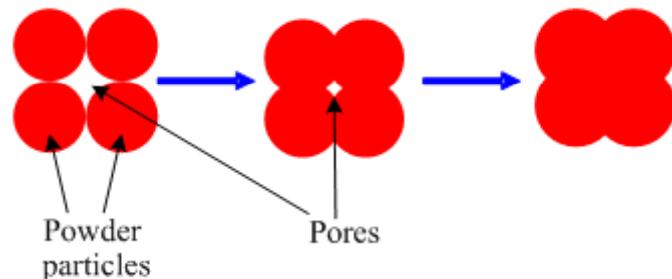
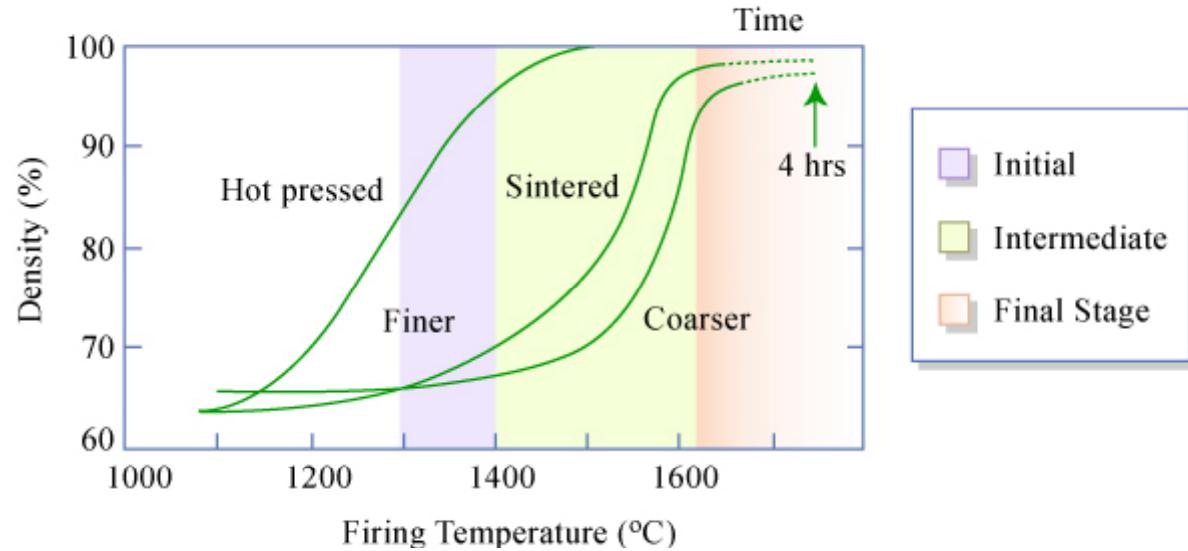
Umberto Anselmi-Tamburini

*Department of Chemistry
University of Pavia
Italy*



MECHANISMS OF SINTERING

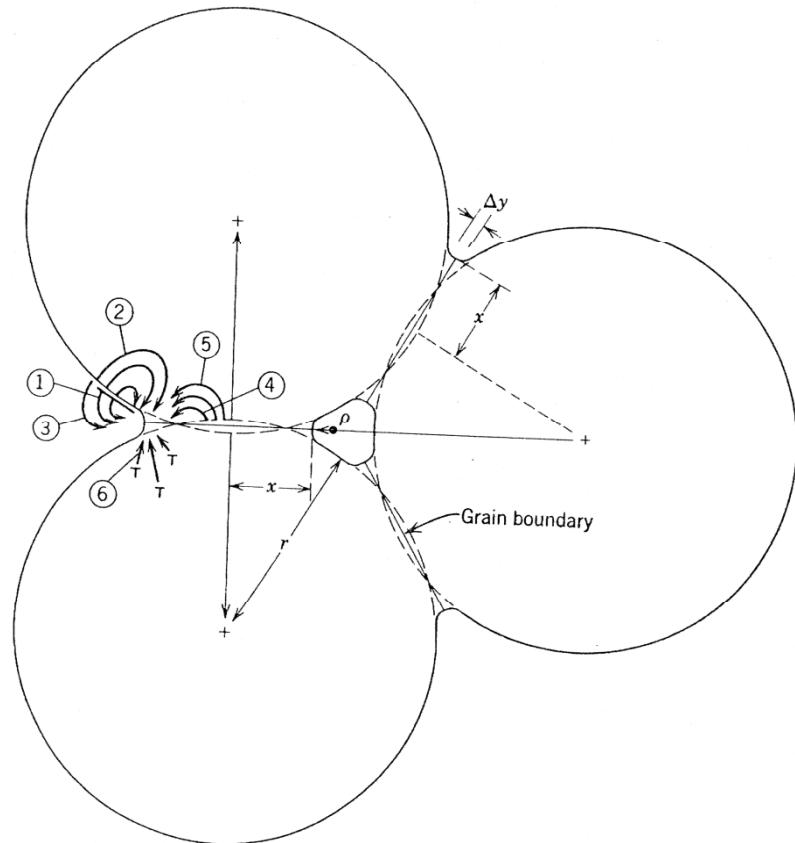
Sintering requires mass transfer through diffusion



The mechanism of mass transfer depends on the material, the experimental conditions, and the sintering stage



MECHANISMS OF SINTERING

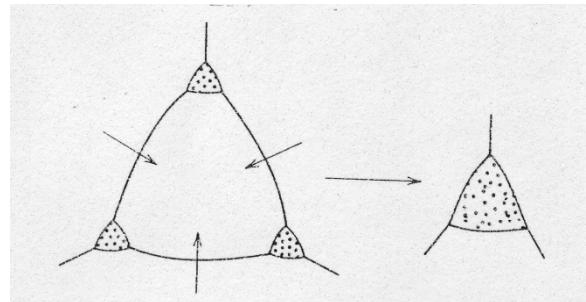
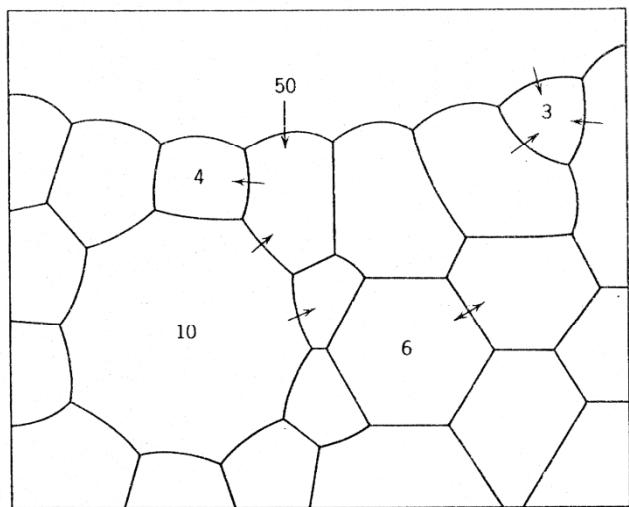
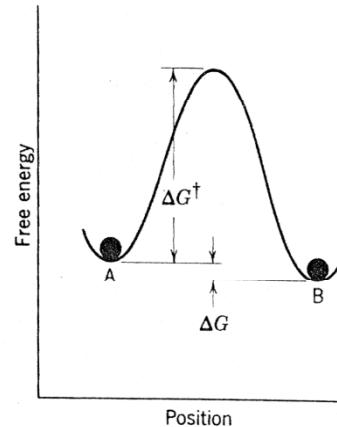
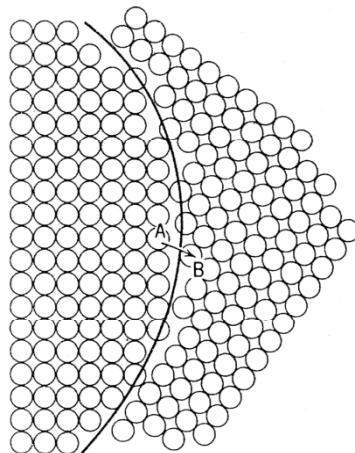


Mechanism Number	Transport Path	Source of Matter	Sink of Matter
1	Surface diffusion	Surface	Neck
2	Lattice diffusion	Surface	Neck
3	Vapor transport	Surface	Neck
4	Boundary diffusion	Grain boundary	Neck
5	Lattice diffusion	Grain boundary	Neck
6	Lattice diffusion	Dislocations	Neck

W.D.Kingery, H.K.Bowen, D.R.Uhlmann, Introduction to ceramics , Wiley



MECHANISMS OF SINTERING



W.D.Kingery, H.K.Bowen, D.R.Uhlmann, Introduction to ceramics , Wiley



MECHANISMS IN FAST SINTERING



- FAST sintering involves experimental conditions more complex than in traditional sintering, so **more** mass transfer mechanisms might be involved
- The number of involved mechanisms and their relative relevance is still being debated
- It is very dependent on the material physical and chemical properties and on the experimental conditions



MECHANISMS IN FAST SINTERING



- Arc and spark discharge
- Electromigration
- Electric field induced diffusion
- Temperature gradients
- Pressure and stress gradient
- Modification of defects concentration
- Heating rate



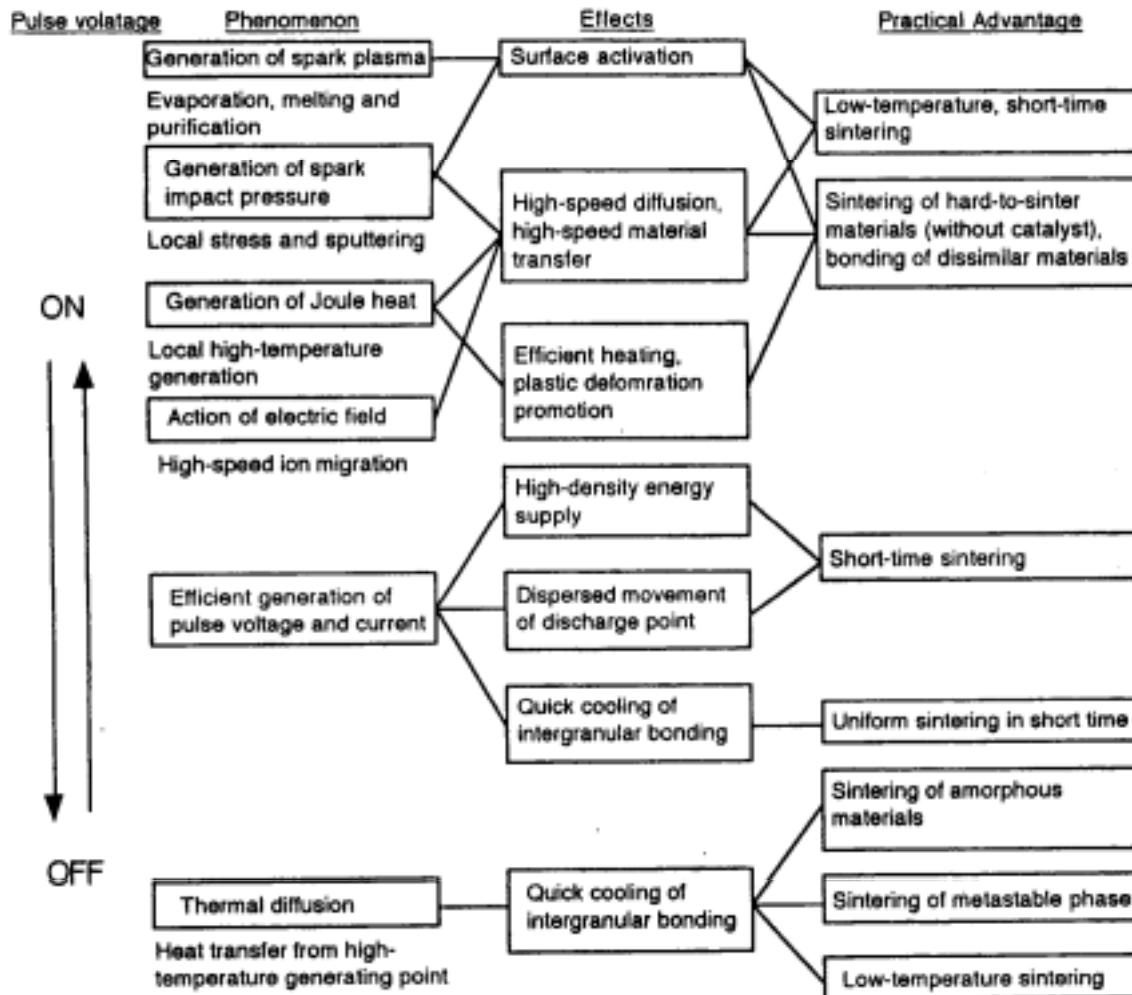
MECHANISMS IN FAST SINTERING



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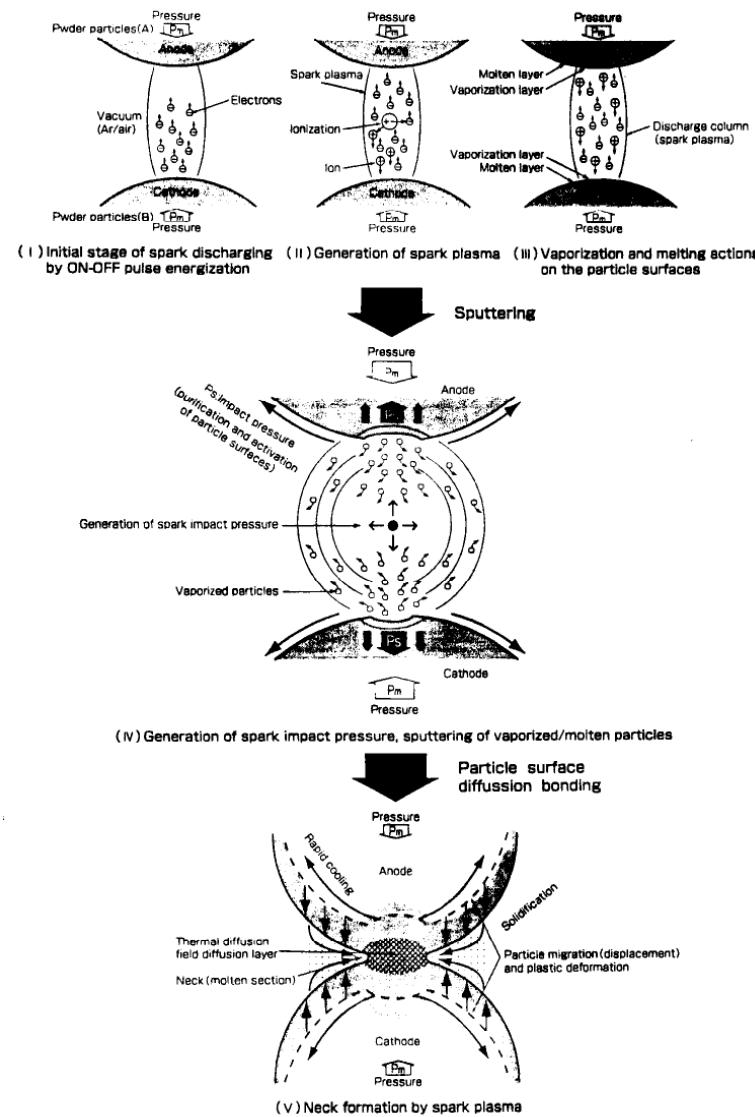
MECHANISMS IN FAST SINTERING



M.Tokita, Proc. NEDO Int. Symp. Functionally Graded Materials, Kyoto, Japan, 1999



ARC AND SPARK DISCHARGE



M.Tokita, Proc. NEDO Int. Symp. Functionally Graded Materials, Kyoto, Japan, 1999



ARC AND SPARK DISCHARGE



- **Arc discharge**

high current (>10 A) and low voltage (< 20 V)

- **Spark discharge**

transient very high current (kA) and voltage (kV/cm)

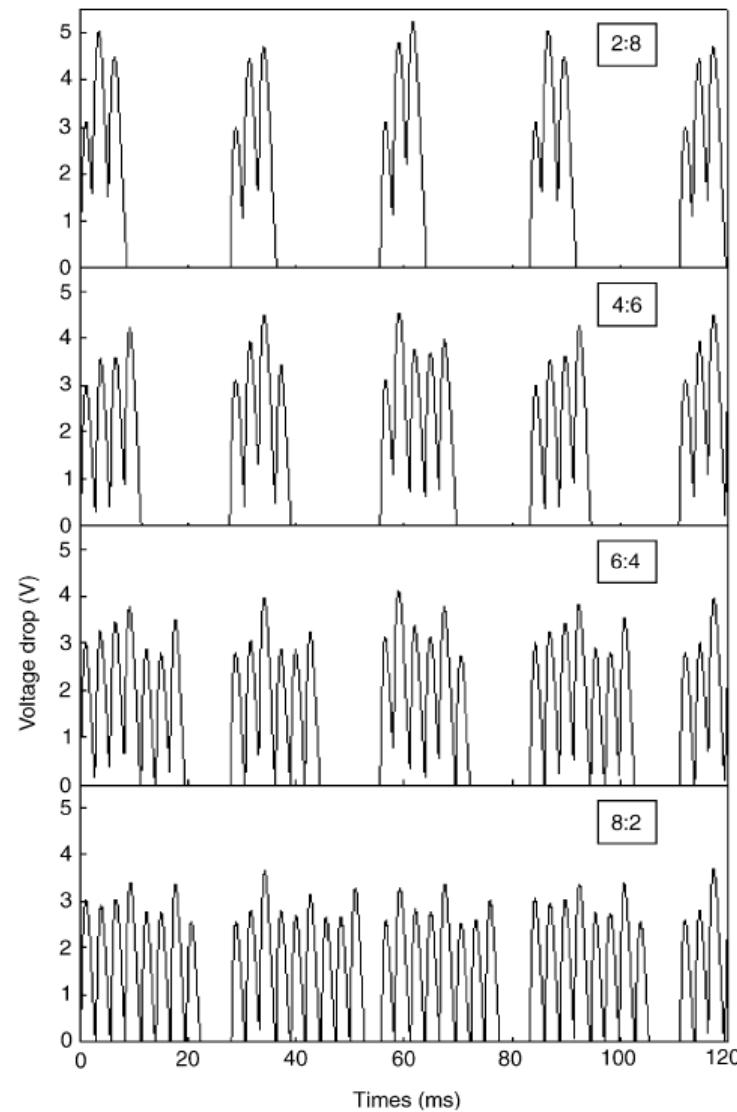
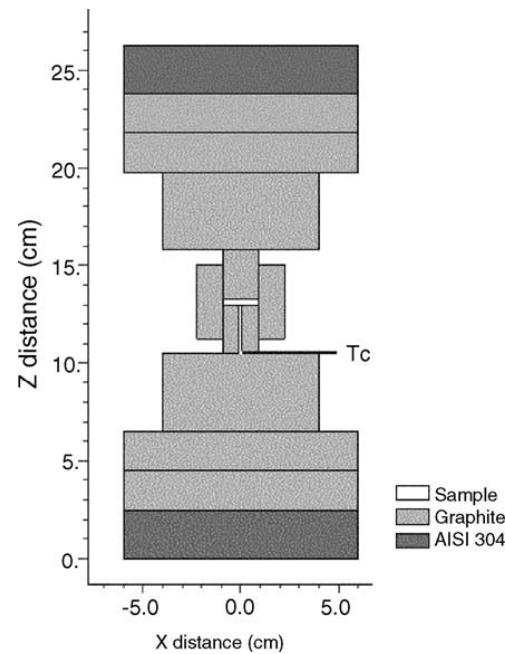
- **Glow discharge**

low current (< 1 A) and relatively high voltage (300 V)



ARC AND SPARK DISCHARGE

What is the voltage that the sample experience in a FAST apparatus?



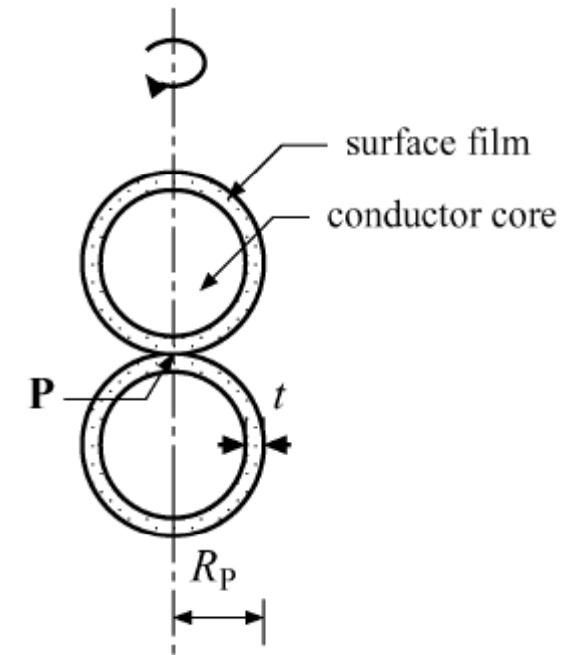
U. Anselmi-Tamburini, S. Gennari, J.E. Garay, Z.A. Munir, Mat. Sci. Eng. A 394 (2005) 139–148



ARC AND SPARK DISCHARGE



The imposed fields are just few volts, but polarization effects can produce localized fields order of magnitude higher

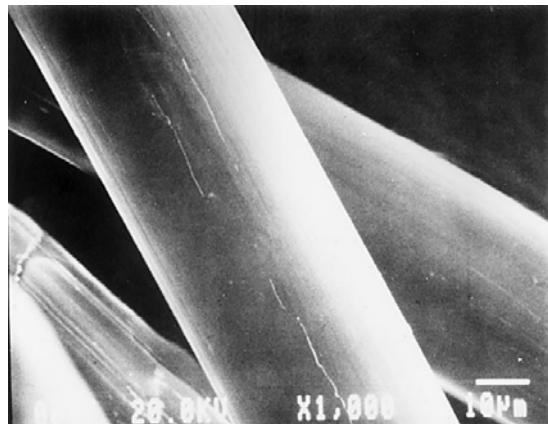




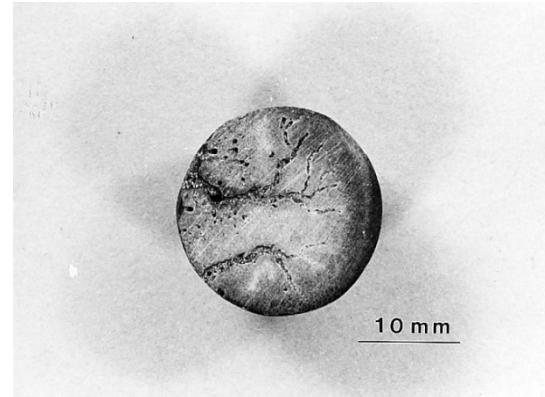
ARC AND SPARK DISCHARGE



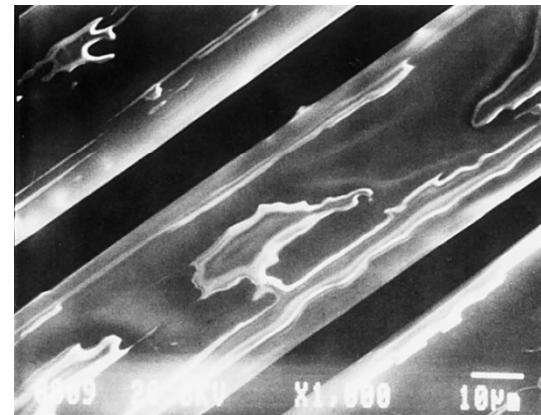
Evidences supporting the presence of discharges



SEM image of polyethylene fiber.



Electric discharge pattern on the surface of CeSiNO₂.



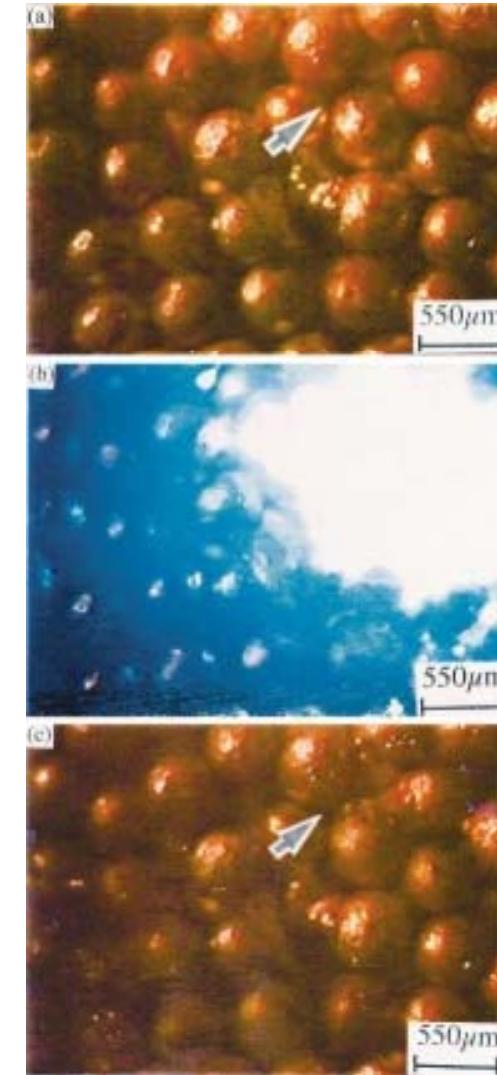
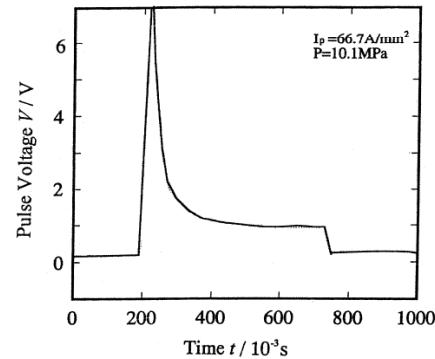
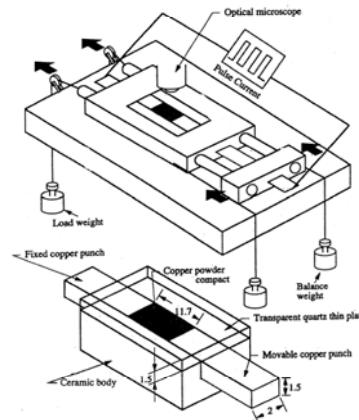
SEM image of the polyethylene fiber exposed to electrical discharge in air.

M. Omori : Materials Science and Engineering A287 (2000) 183–188



ARC AND SPARK DISCHARGE

Evidences supporting the presence of discharges



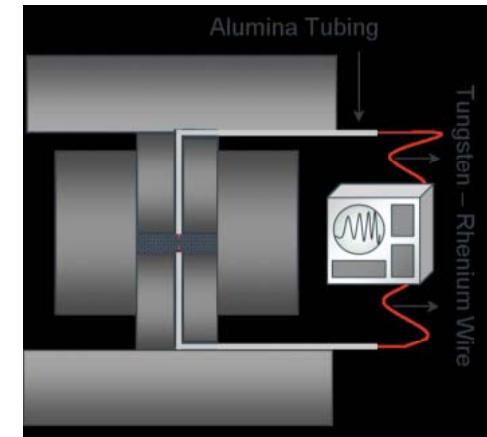
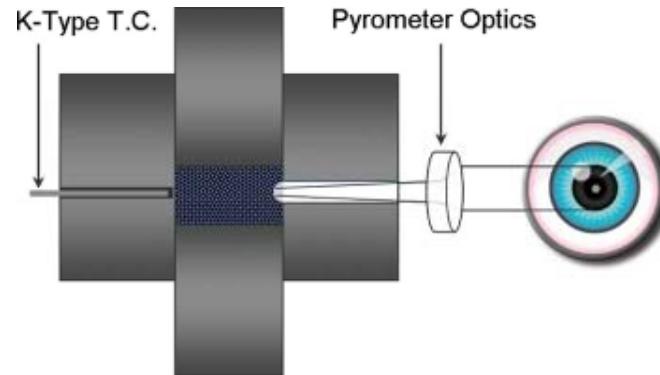
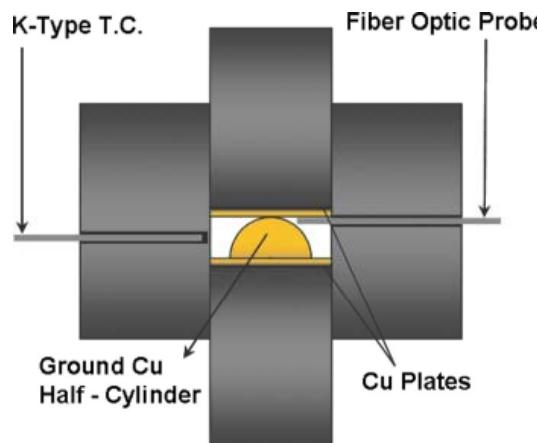
O. Yanagisawa et al. / Materials Science and Engineering A350 (2003) 184/189



ARC AND SPARK DISCHARGE



Evidences against the presence of discharges



D.M. Hulbert, A. Anders, D. V. Dudina, J. Andersson, D. Jiang, C. Unuvar, U. Anselmi-Tamburini, E. J. Lavernia, and A.K. Mukherjee, *J. Appl. Phys.* 104 (2008) 033305

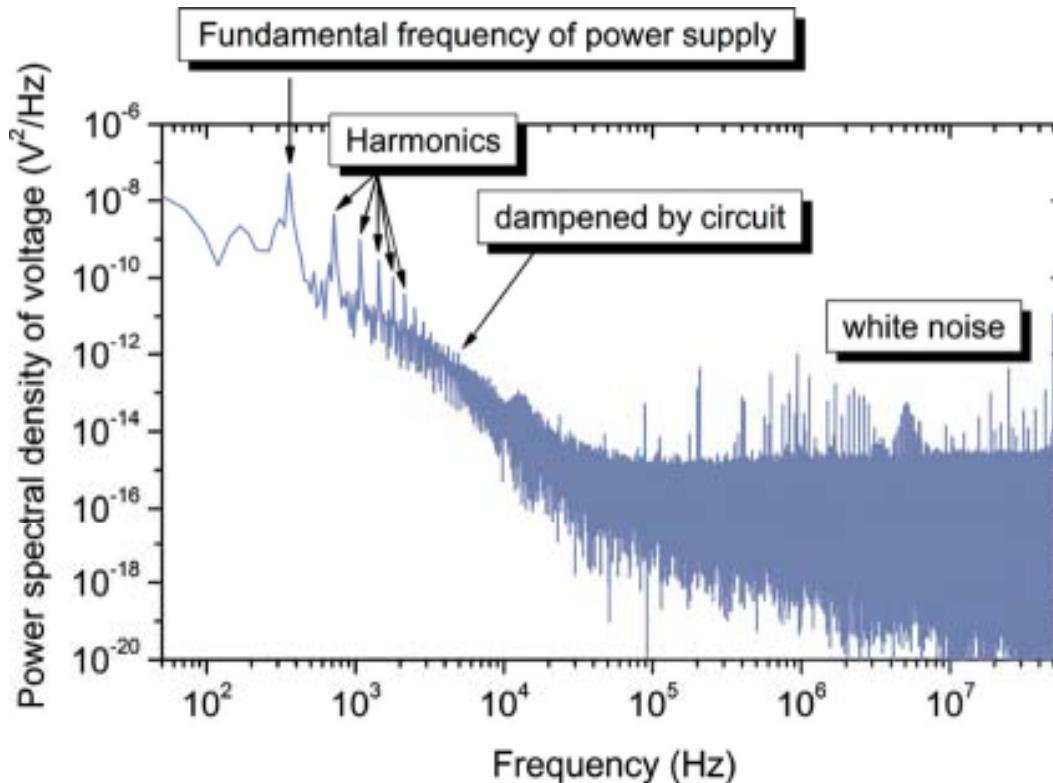
Umberto Anselmi-Tamburini

Basic mechanisms involved in FAST sintering



ARC AND SPARK DISCHARGE

Evidences against the presence of discharges



A FFT plot of one duty cycle of the SPS process. This plot is for the SPS of 325 mesh 99.9% pure Al powder after a temperature of 100 °C was reached using a heating rate of 100 °C/min.

D.M. Hulbert, A. Anders, D. V. Dudina, J. Andersson, D. Jiang, C. Unuvar, U. Anselmi-Tamburini, E. J. Lavernia, and A.K. Mukherjee, *J. Appl. Phys.* 104 (2008) 033305



MECHANISMS IN FAST SINTERING



- Arc and spark discharge
- **Electromigration**
- Electric field induced diffusion
- Temperature gradients
- Pressure and stress gradient
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- Heating rate



DIFFUSION AND EXTERNAL DRIVING FORCES



$$J = -D \frac{\partial C}{\partial x} + \boxed{\tilde{v} C}$$

$$\tilde{v} = uF$$

u is the mobility
 F the driving force

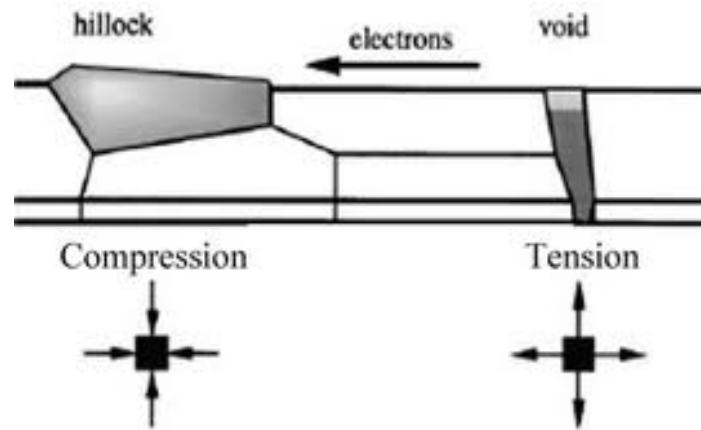
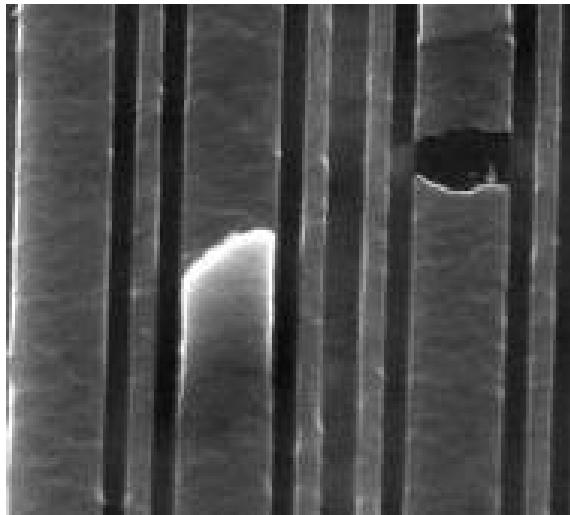
Force	Expression	Remarks
Gradient of electrical potential $E = -\nabla U$	$q^* E$	q^* : effective electric charge
Gradient of chemical potential (non-ideal part)	$-\nabla \mu$	μ : chemical potential
Temperature gradient ∇T	$-(Q^*/T)\nabla T$ or $-S\nabla T$	Q^* : heat of transport S : Soret coefficient
Stress gradient	$-\nabla U_{el}$	U_{el} : elastic interaction energy due to stress field



ELECTROMIGRATION



- Correlation between ionic and electronic conduction.
- Usually observed in metals for current densities $> 1000 \text{ A/cm}^2$
- Huge importance in semiconductor industry





ELECTROMIGRATION



$$J = -D \frac{\partial C}{\partial x} + u F C$$

For electromigration:

$$\begin{aligned} F &= |e| Z^* E \\ &= |e| (Z^e + Z^w) E \end{aligned}$$

Z^e electrostatic interaction
 Z^w “wind effect”

If the mobility is given by the Nernst-Einstein equation : $u = \frac{D}{kT}$

$$\begin{aligned} J &= -D \frac{\partial C}{\partial x} + \frac{DC}{kt} Z^* |e| E \\ &= -D \frac{\partial C}{\partial x} + \frac{DC}{kt} Z^* |e| \rho j \end{aligned}$$

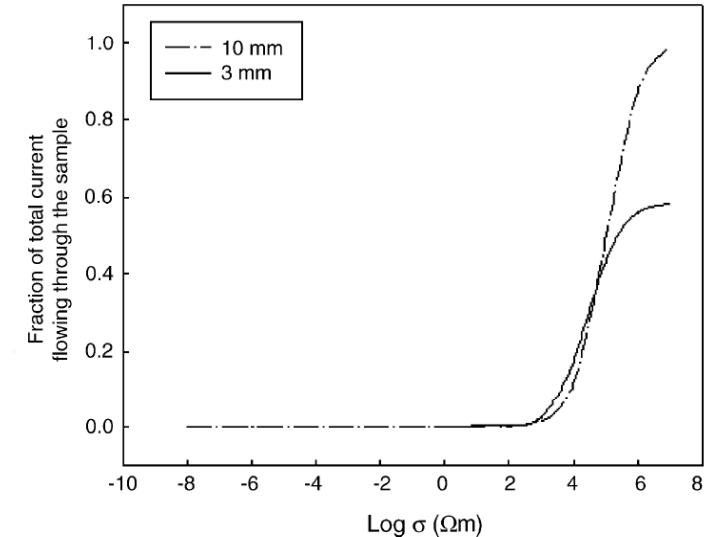
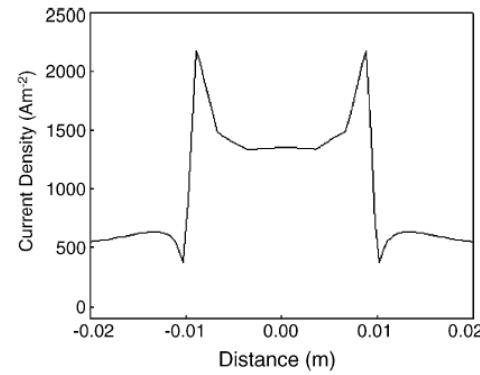
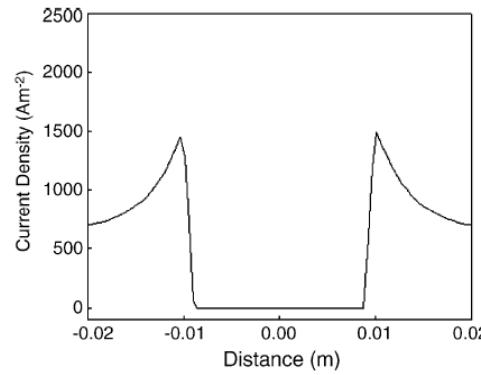
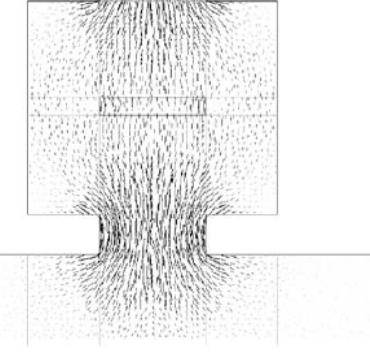
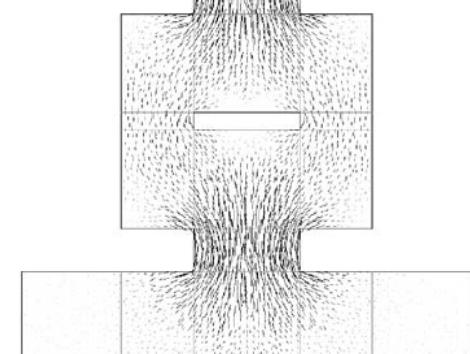
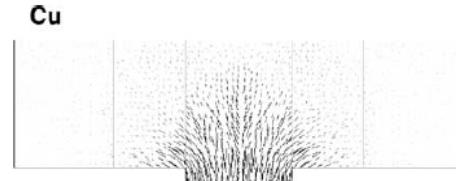
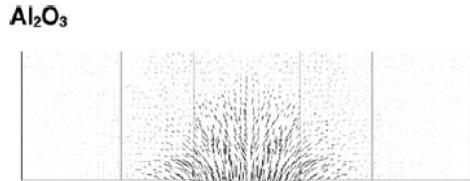
Vacancy diffusion in metals

D.G. Pierce and P. G. Brusius,, *Microelectron. Reliab.*, Vol. 37, No. 7, pp. 1053 -1072, 1997



ELECTROMIGRATION

How much current flows through the sample in a FAST system?

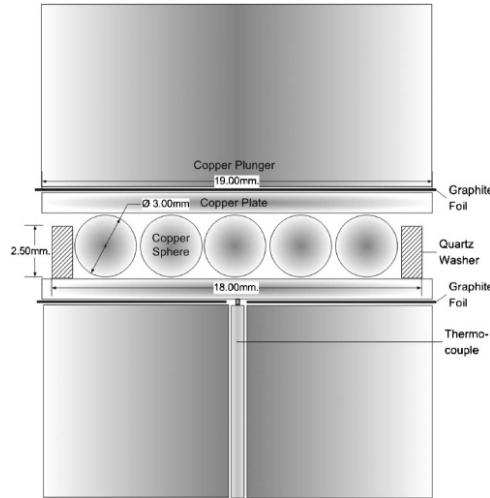


U. Anselmi-Tamburini, S. Gennari, J.E. Garay, Z.A. Munir, Materials Science and Engineering A 394 (2005) 139–148

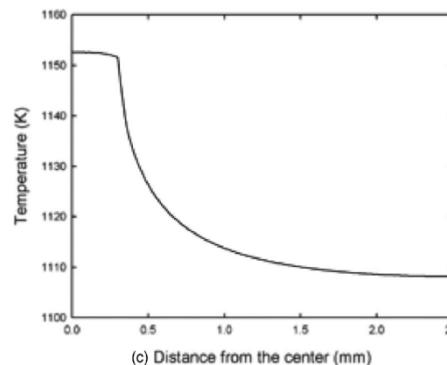
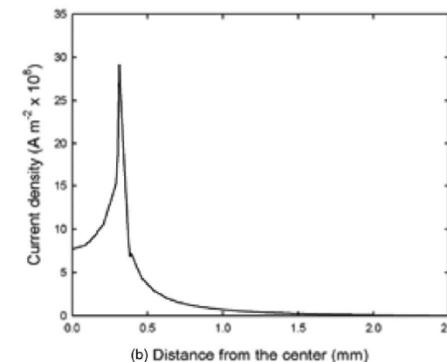
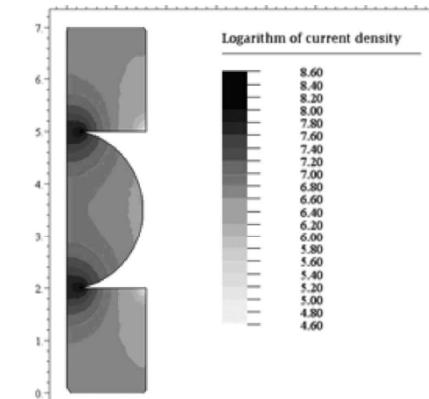
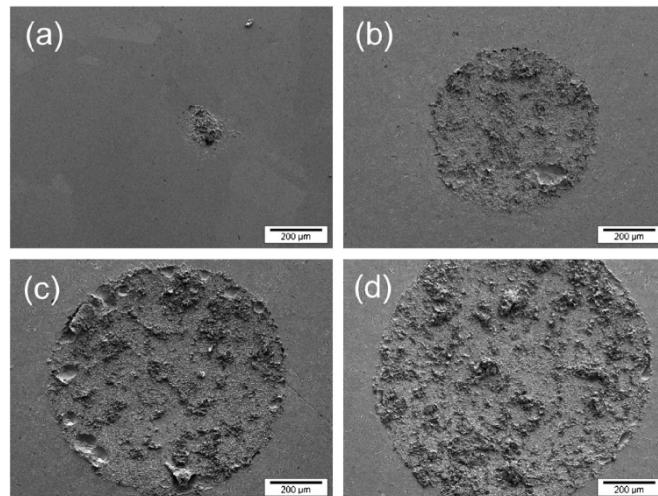


ELECTROMIGRATION AND SINTERING

Copper spheres on Copper plate



900 °C
60 min
a) 0 A
b) 700 A
c) 850 A
d) 1040 A.



J.M. Frei, U.Anselmi-Tamburini, Z.A. Munir, J. Appl. Phys. 101 (2007) 114914



ELECTROMIGRATION AND GRAIN BOUNDARIES



$$J_l = \frac{1}{kT} N_l D_l j \rho e Z_l^*$$

δ boundary width
 d grain size

$$J_b = \frac{1}{kT} \frac{N_b \delta}{d} j \rho e Z_b^*$$

$$\frac{J_l}{J_b} = \frac{N_l}{N_b} \frac{\delta}{d} \frac{D_l}{D_b} \frac{Z_l^*}{Z_b^*} j \rho e$$

Z_l^* and Z_b^* do not differ by more than an order of magnitude, so for Al with $d=1\mu m$ and $0.5 T_m$:

$$\frac{N_l}{N_b} \cong 1 \quad \frac{\delta}{d} \cong 10^3 \quad \frac{D_l}{D_b} \cong 10^{-7} \quad \frac{J_l}{J_b} \cong 10^{-4}$$

P.S.Ho and T.Kwok, Rep.Prog.Phys., 52 (1989) 301



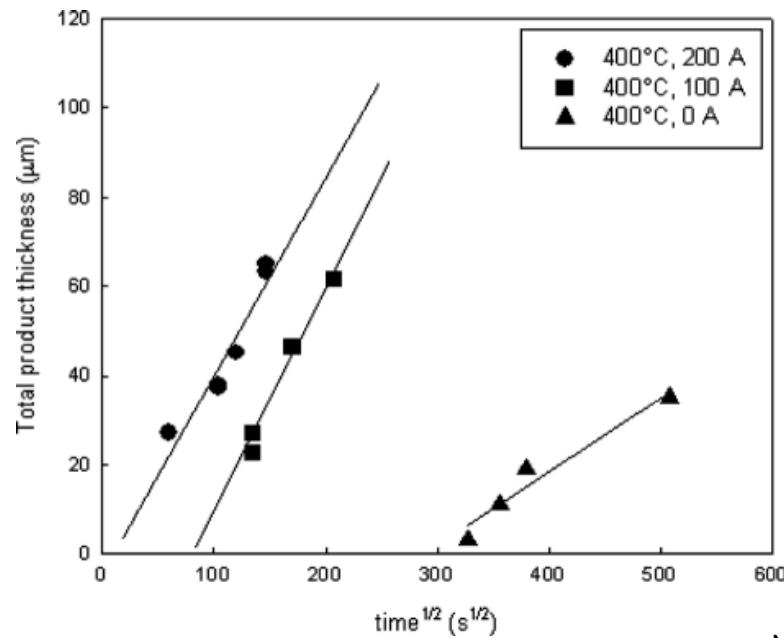
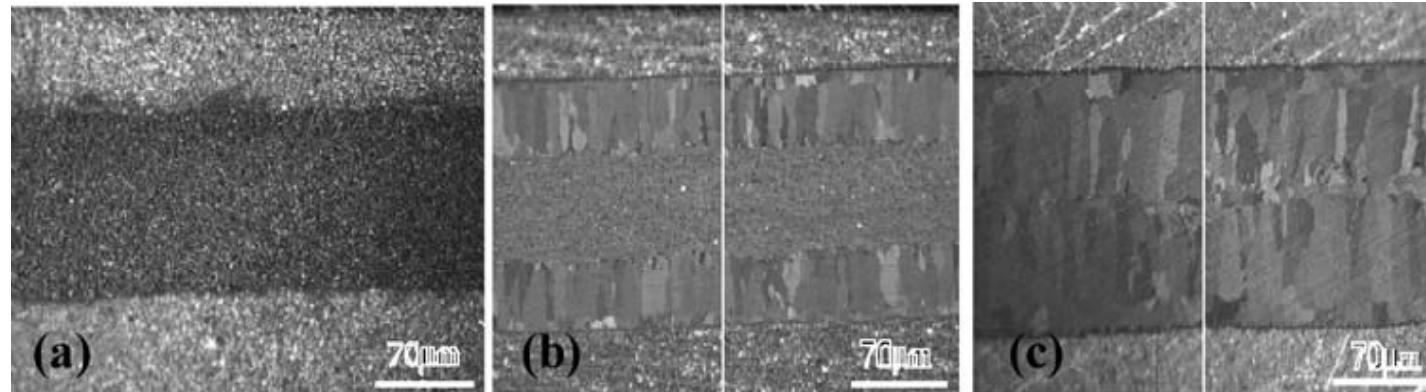
ELECTROMIGRATION AND REACTIVITY

Formation of intermetallic compounds

Al

Au

Al



The enhancement depends on the intrinsic diffusivity and on the magnitude of the electromigration on the various species

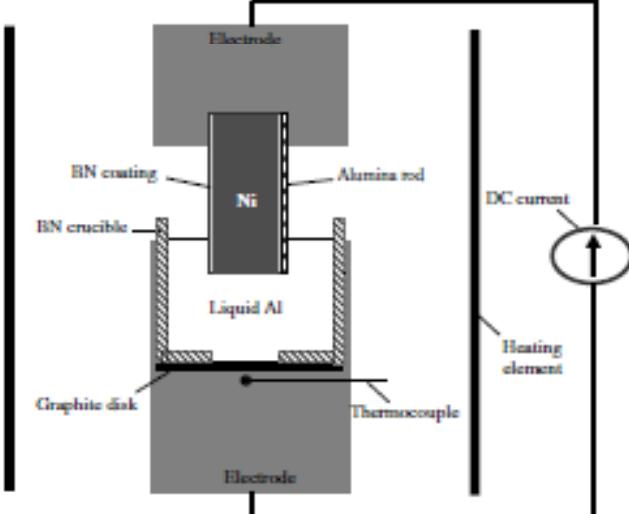
A general phenomenological model has been developed by C.-M. Hsu, D. S.-H. Wong, S.-W. Chen, J.Appl.Phys., 102 (2007) 023715

N.Bertolino, J.Garay, U.Anselmi-Tamburini, Z.A.Munir, Phil.Mag.B, 82 (2002) 969

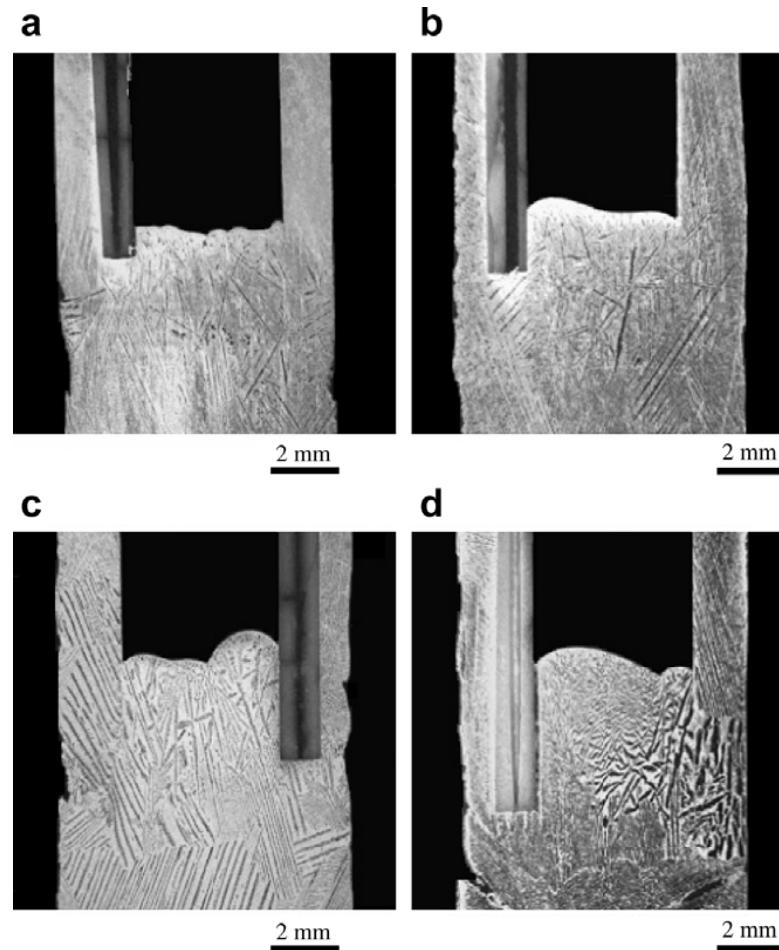


ELECTROMIGRATION IN SOLID-LIQUID REACTIVITY

Formation of intermetallic compounds



767°C , 15 min
(a) 0 A/cm²
(b) 316 A/cm²
(c) 474 A/cm²
(d) 585 A/cm²



J.F. Zhao, C. Unuvar, U. Anselmi-Tamburini, Z.A. Munir , Acta Materialia 55 (2007) 5592–5600



MECHANISMS IN FAST SINTERING



- Arc and spark discharge
- Electromigration
- **Electric field induced diffusion**
- Temperature gradients
- Pressure and stress gradient
- Modification of defects concentration
- Heating rate



FIELD INDUCED DIFFUSION IN IONIC MATERIALS



Diffusion under the influence of an external driving force

$$J = -D \frac{\partial C}{\partial x}$$

$$\tilde{v} = uF$$

u is the mobility
 F is the driving force

In a ionic crystal the electric field produce a flux of material

$$F = qE$$

$$u = \frac{D}{kT}$$

$$j = \tilde{v}C = \frac{qCD}{kT} E$$

Material flux

$$j_e = q j = \frac{q^2 CD}{kT} E$$

Electric current

$$j_e = \sigma E$$
$$\sigma = \frac{q^2 CD}{kT}$$



FIELD INDUCED DIFFUSION IN IONIC MATERIALS

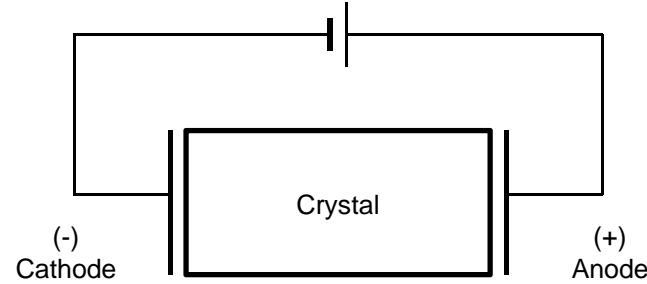


- In ionic materials conduction is related to the defects concentration and mobility.
 - Ionic and electronic defects concentrations are controlled by complex equilibria
-
- Purely ionic conductors
 - Mixed conductors

When ionic conduction is associated to trasfer of material there is the possibility of field induced sintering or densification



FIELD INDUCED DIFFUSION IN IONIC MATERIALS



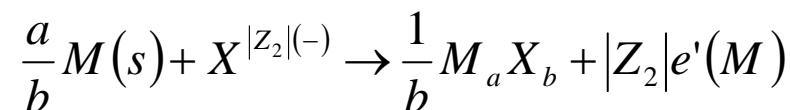
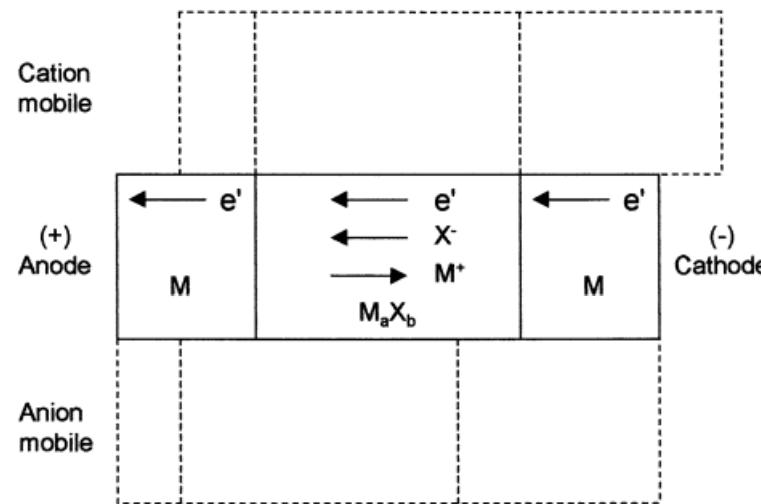
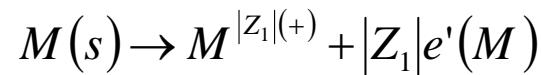
Four kind of electrodes

- Reversible to electrons and ions
- Semi-blocking ionic (passing only ionic current)
- Semi-blocking electronic (passing only electronic current)
- Blocking (passing neither ionic nor electronic currents) – *non contact field*



FIELD INDUCED DIFFUSION IN IONIC MATERIALS

Mixed conductor – identical reversible electrodes

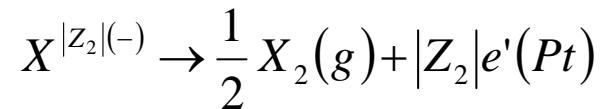
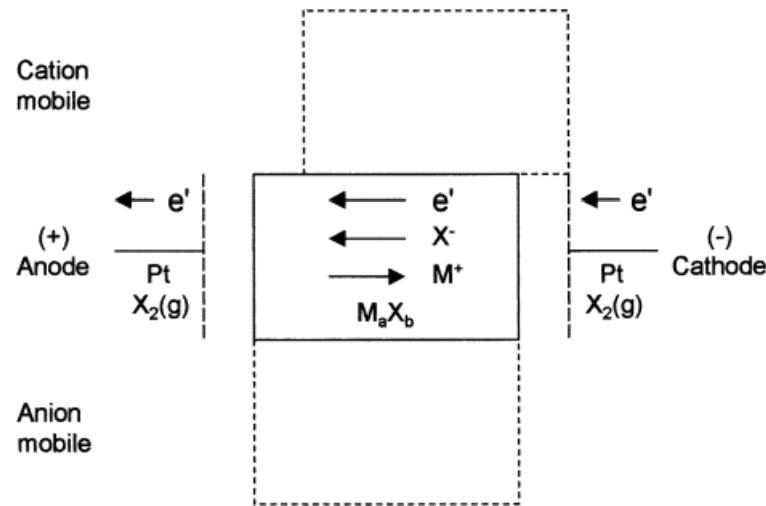
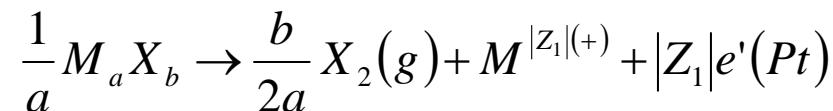


S.C. Byeon, K.S. Hong, Mat.Sci.Eng., A287 (2000) 159-170



FIELD INDUCED DIFFUSION IN IONIC MATERIALS

Mixed conductor – reversible identical gas electrodes

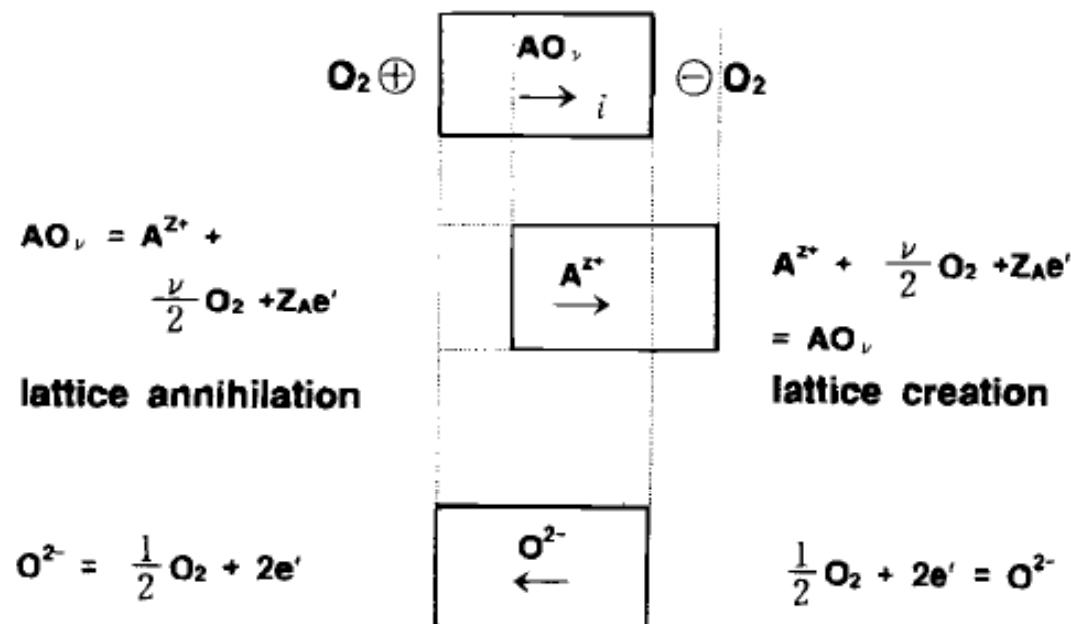




FIELD INDUCED DIFFUSION IN IONIC MATERIALS



Tubandt electrotransport experiment

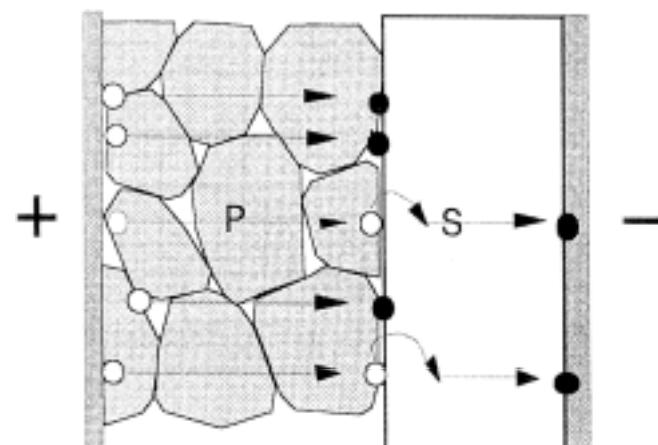
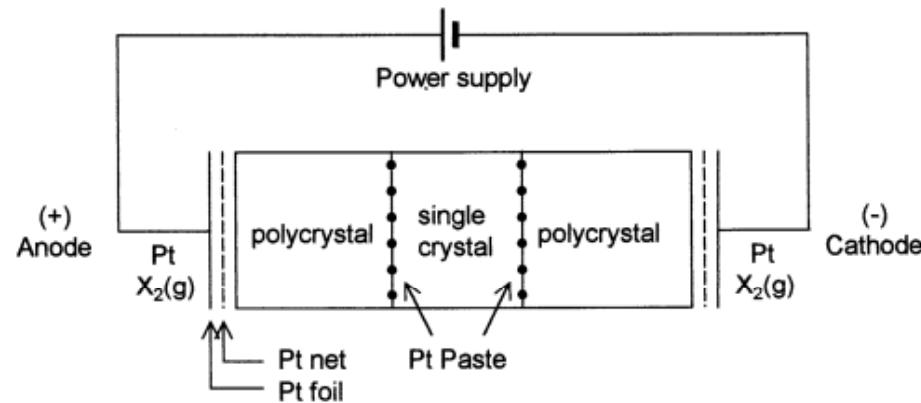


C.-S.Kim, H.-I.Yoo, J.Electrochem.Soc., 143 (1996) 2863

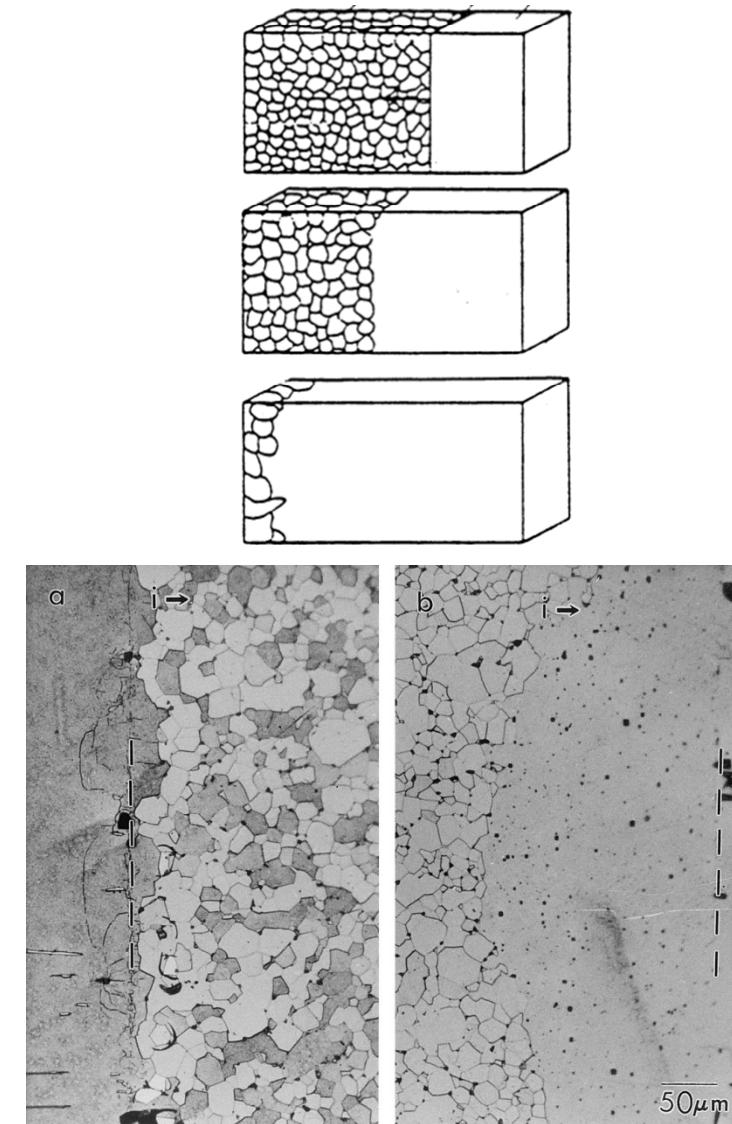


FIELD INDUCED DIFFUSION IN IONIC MATERIALS

Electrotransport and sintering



P : Polycrystal S : Singlecrystal
○ Cation ● Newly made lattice



S.C. Byeon, K.S. Hong, Mat.Sci. Eng., A287 (2000) 159-170

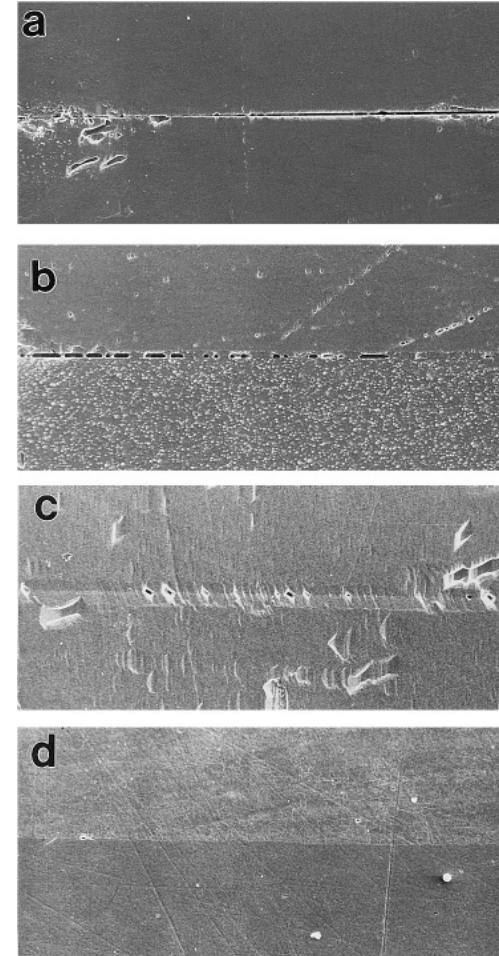
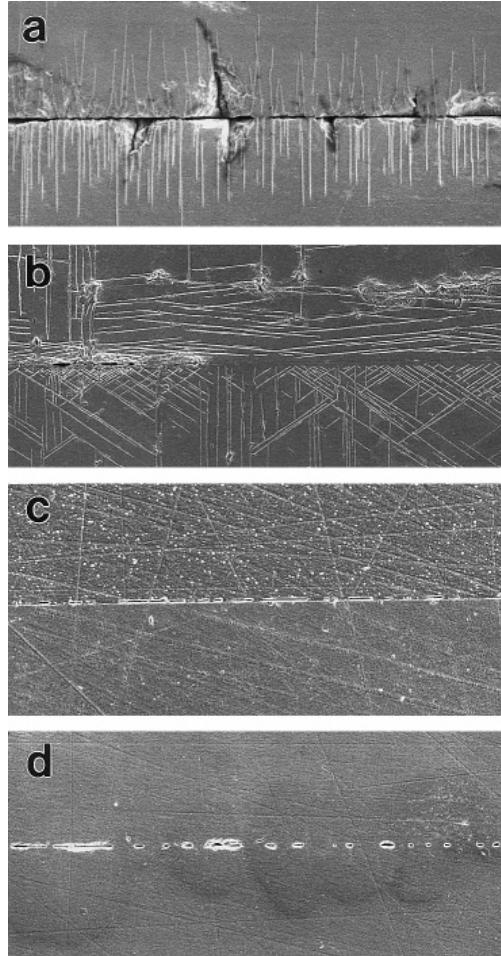


FIELD INDUCED DIFFUSION IN IONIC MATERIALS



Electrotransport and sintering – joining single crystals of ferrite

- (a) 900°C, 12 h, no current
- (b) 900°C, 12 h, 1 A
- (c) 1100°C, 12 h, no current
- (d) 1100°C, 12h, 1 A



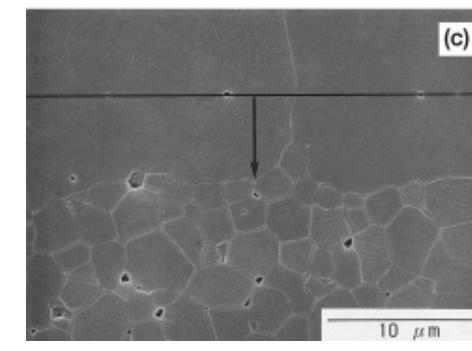
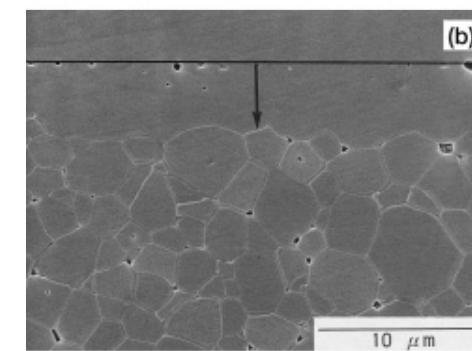
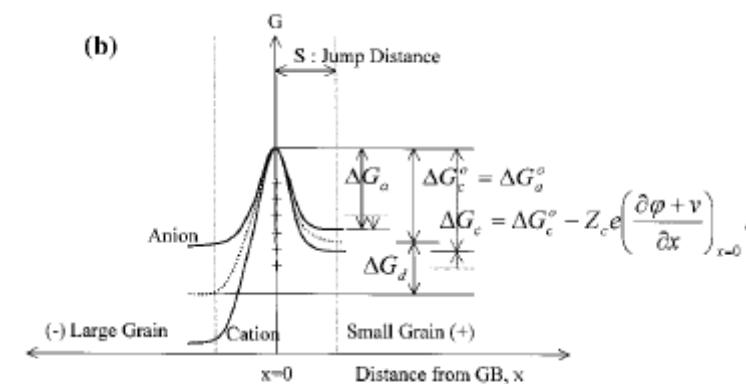
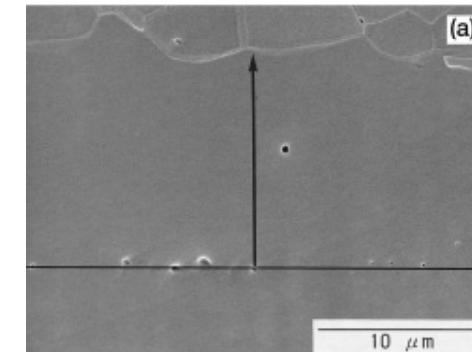
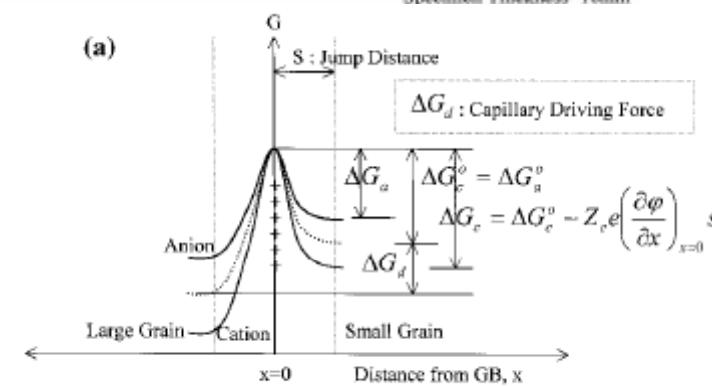
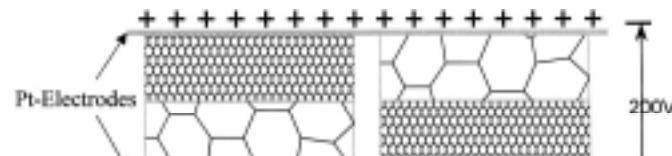
- 1200°C for:
- (a) 3 h, 1 A
 - (b) 6 h, 1 A
 - (c) 12 h, 1 A
 - (d) 24 h, 1 A

S.C. Byeon, K.S. Hong, Mat.Sci. Eng., A287 (2000) 159-170



FIELD INDUCED DIFFUSION IN IONIC MATERIALS

Grain boundary migration in alumina



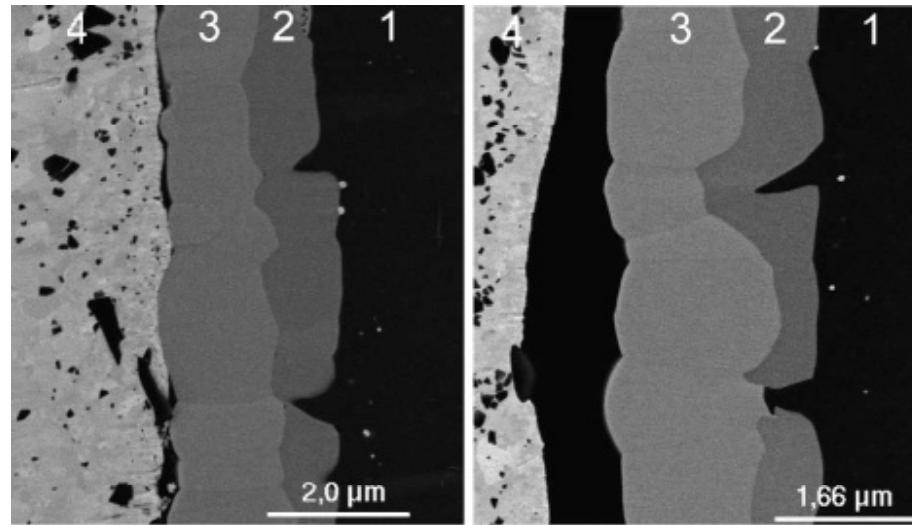
J.-W.Jeong, J.-H.Han, D.-Y.Kim,, J. Am. Ceram. Soc., 83 (2000) 915–18



FIELD INDUCED DIFFUSION IN IONIC MATERIALS

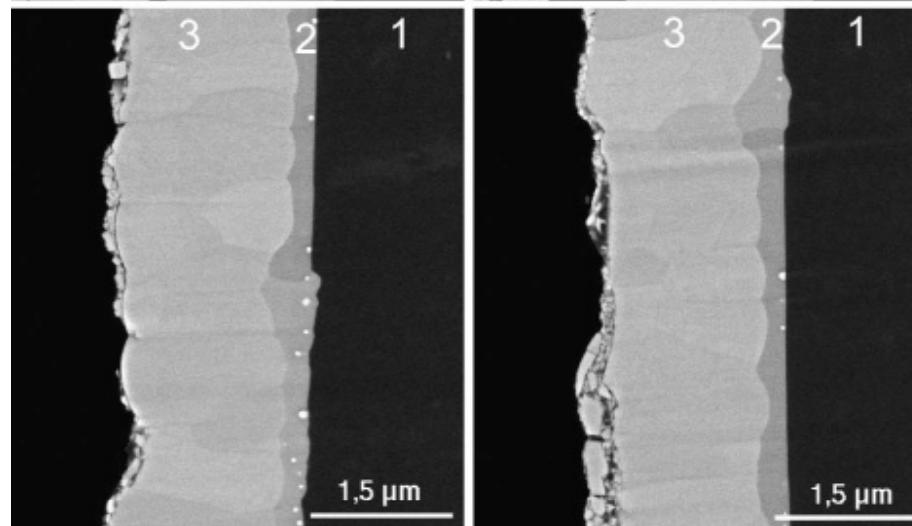
Solid state reaction (reactive sintering)

1350°C
12 min
100 V



- (1)MgO
- (2) $MgIn_2O_4$
- (3) In_2O_3
- (4) Pt cathode

1350°C
12 min
0 V

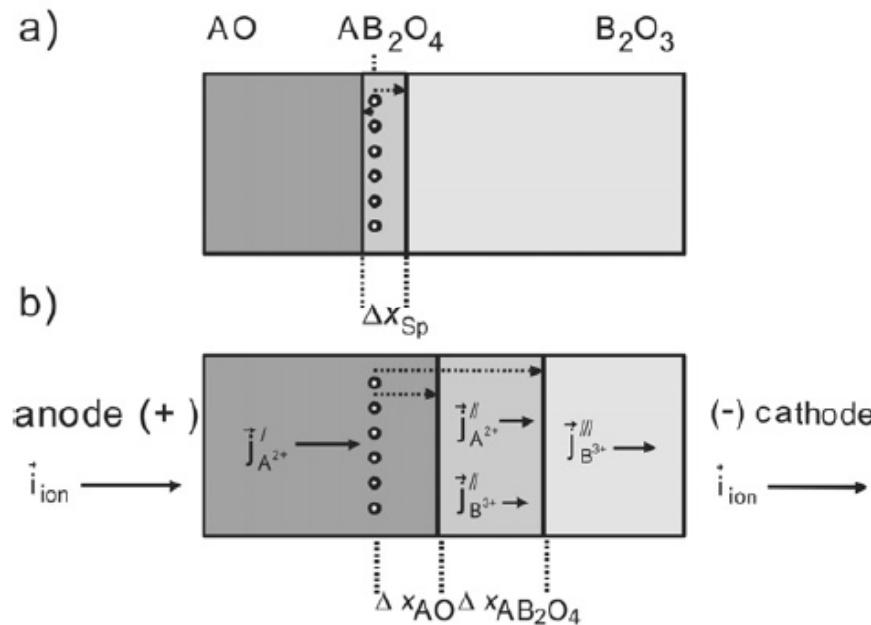
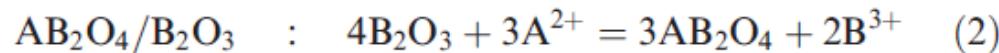


C. Korte, N. Ravishankar, C.B. Carter , H. Schmalzried, Solid State Ionics 148 (2002) 111 –121



FIELD INDUCED DIFFUSION IN IONIC MATERIALS

Solid state reaction (reactive sintering)



- If the ionic current is directed towards B₂O₃, the total growth rate is increased. During its growth the spinel layer shifts towards the cathode.
- If the ionic current is directed towards AO, the growth process ends in a steady state with a constant thickness. The steady state derive from the compensation of the electric and the chemical driving forces.

C. Korte, N. D. Zakharov and D. Hesse, Phys. Chem. Chem. Phys., 2003, 5, 5530–5535



FIELD INDUCED DIFFUSION IN IONIC MATERIALS

Cross-correlation between electronic and ionic conduction

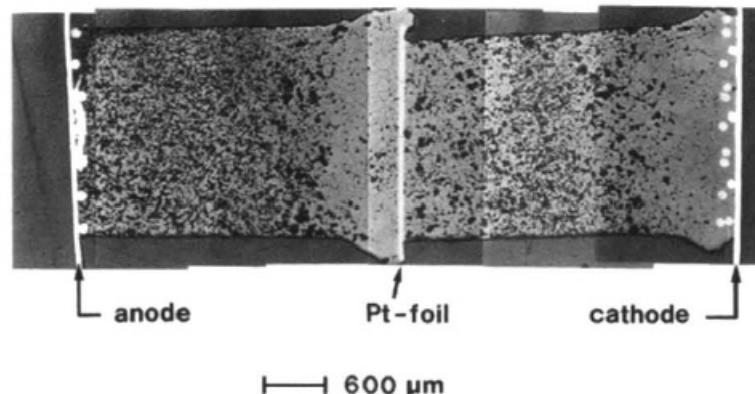
In mixed ionic electronic conductors a flux of mobile ions might be induced not only by a gradient of its own electrochemical potential, but also, indirectly, by a gradient of electrochemical potential of electrons

$$\begin{pmatrix} J_i \\ J_e \end{pmatrix} = - \begin{pmatrix} L_{ii} & L_{ie} \\ L_{ei} & L_{ee} \end{pmatrix} \begin{pmatrix} \nabla \eta_i \\ \nabla \eta_e \end{pmatrix}$$

$L_{ie} = L_{ei}$ Onsager relationship

usually it is considered $L_{ie} = L_{ei} = 0$ meaning that ions and electrons move independently

In some semiconducting oxides this assumption is not valid. This can produce a transfer of matter in presence of intense electronic fluxes

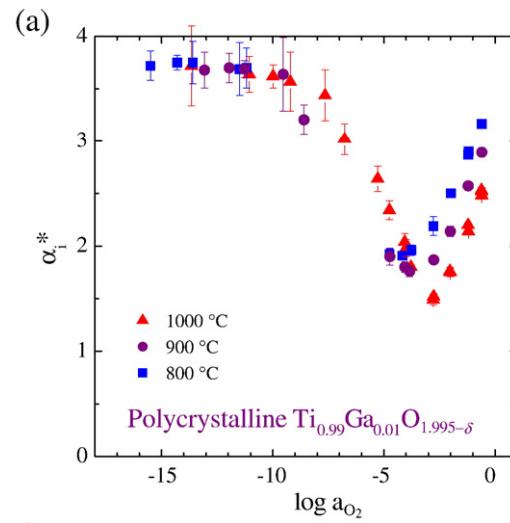


H.-I. Yoo, D.-K. Lee, Solid State Ionics 179 (2008) 837–841

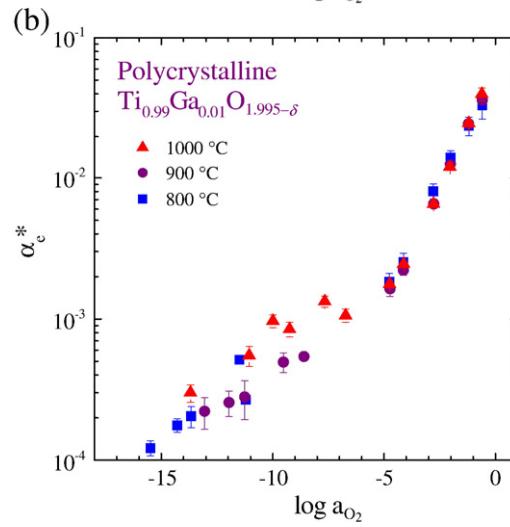


FIELD INDUCED DIFFUSION IN IONIC MATERIALS

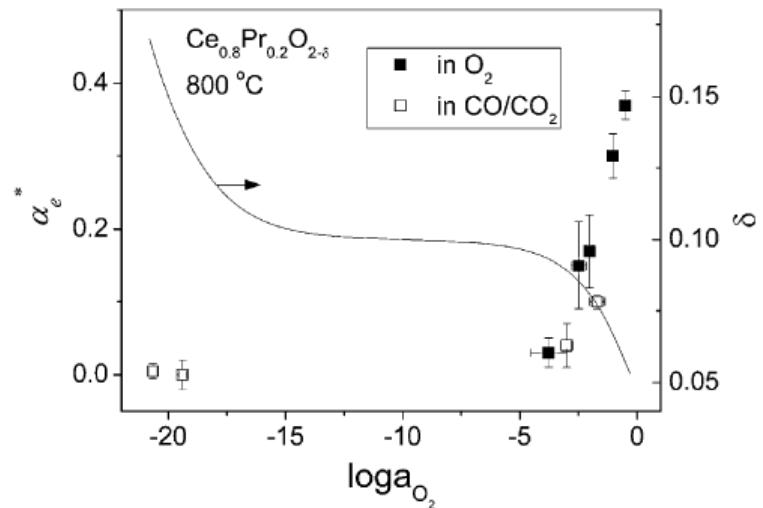
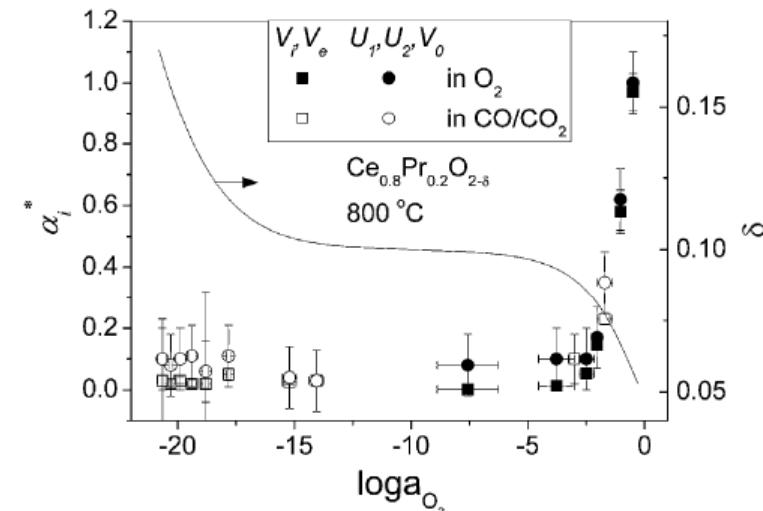
Cross-correlation between electronic and ionic conduction



$$\alpha_i^* = \frac{L_{ei}}{L_{ii}} = \left(\frac{J_e}{J_i} \right)_{\nabla \eta_e = 0}$$



$$\alpha_e^* = \frac{L_{ie}}{L_{ee}} = \left(\frac{J_i}{J_e} \right)_{\nabla \eta_i = 0}$$





MECHANISMS IN FAST SINTERING

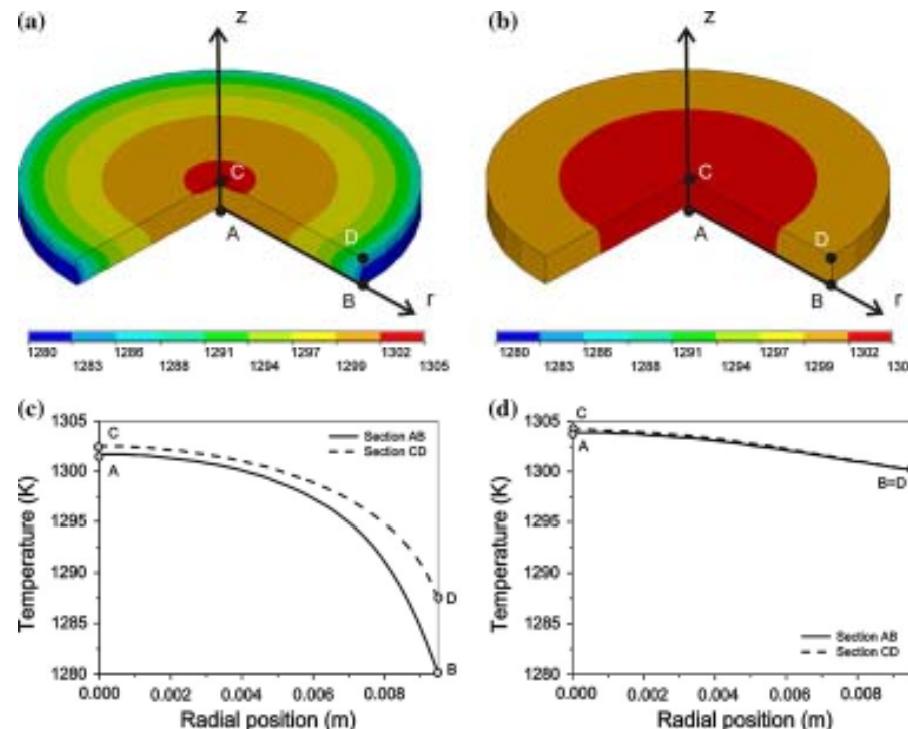
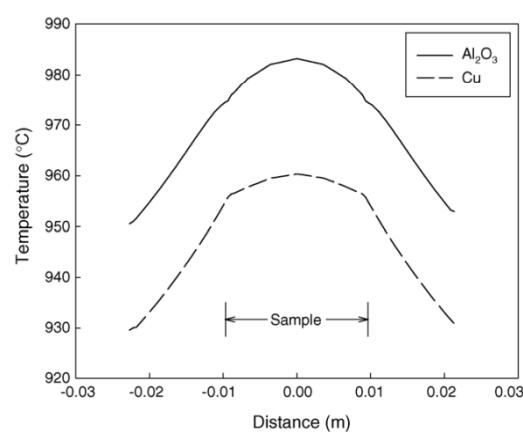
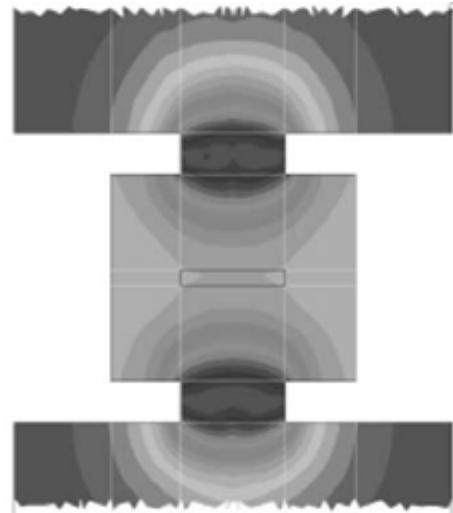


- Arc and spark discharge
- Electromigration
- Electric field induced diffusion
- **Temperature gradients**
- Pressure and stress gradient
- Modification of defects concentration
- Heating rate



TEMPERATURE GRADIENTS AND DIFFUSION

Macroscopic temperature gradients





TEMPERATURE GRADIENTS AND DIFFUSION



Macroscopic temperature gradients

Soret effect (thermotransport or thermomigration)

$$J = -D \frac{\partial C}{\partial x} + uFC$$

$$J = -D \frac{\partial C}{\partial x} - S \frac{\partial T}{\partial x} \qquad Q^* \equiv \frac{S}{T} \quad \text{Heat of transport}$$

At the steady state

$$\left(\frac{\partial C}{\partial x} \right)_{ss} = - \frac{S}{D} \left(\frac{\partial T}{\partial x} \right)_{ss} \qquad S \text{ can be either negative or positive}$$

For vacancy distribution in a metal h_{fv}
enthalpy of formation for a vacancy

$$J_v = - \frac{D_v N c_v \nabla T}{k T^2} (h_{fv} + q_v^*)$$



TEMPERATURE GRADIENTS AND DIFFUSION

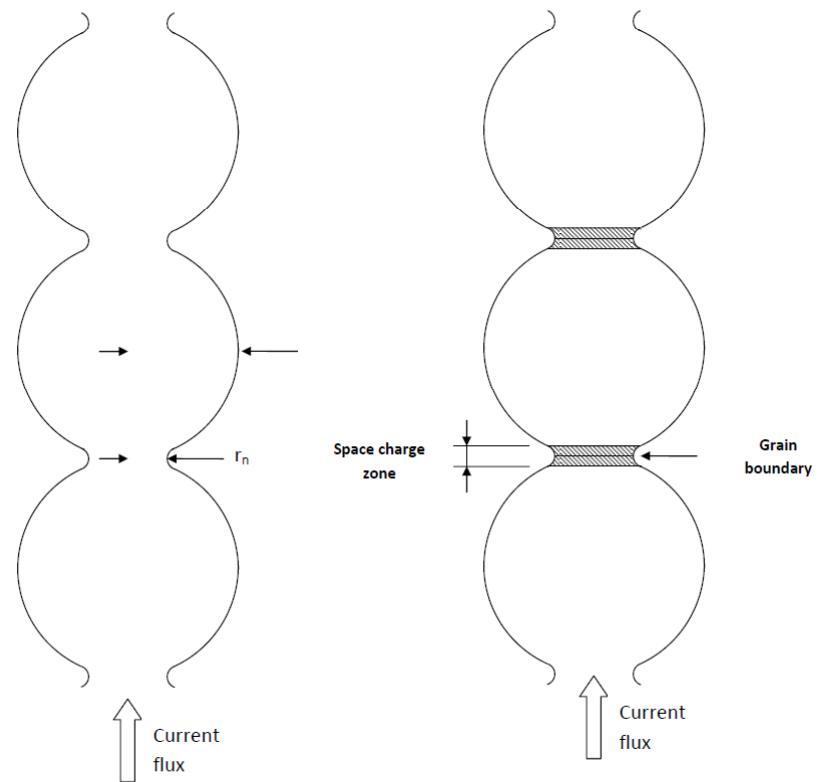


Microscopic temperature gradients

Within the single grain. Two main causes:

- 1) Cross section restriction
- 2) Grain boundary resistance

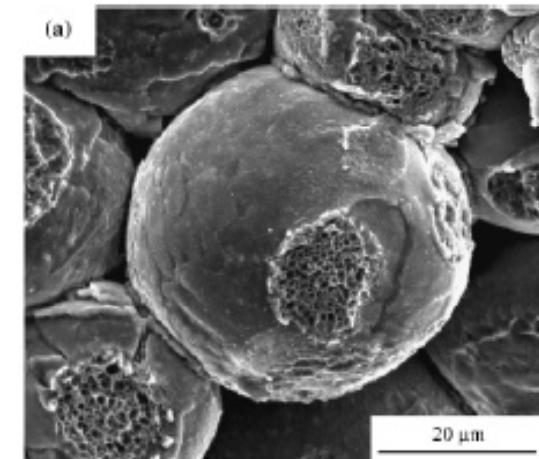
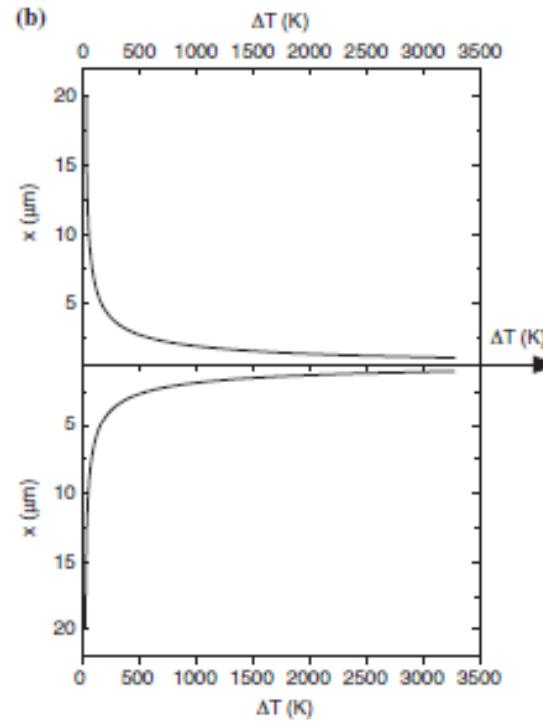
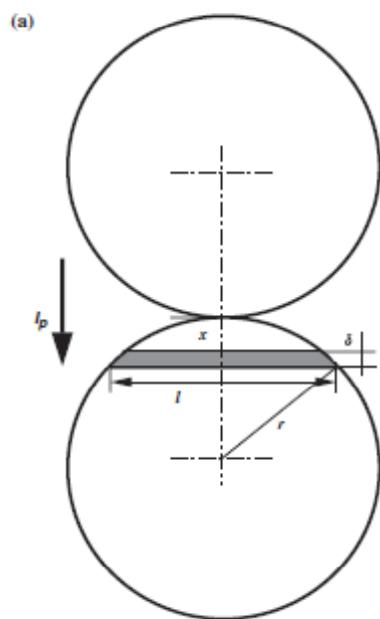
It has been suggested that microscopic temperature gradients are related to flash sintering and to retarded grain growth





TEMPERATURE GRADIENTS AND DIFFUSION

Microscopic temperature gradients – cross section restriction



Localized Soret effect

Localized enhanced diffusivity, melting and vaporization

X.Song, X. Liu, J.Zhang, J. Am. Ceram. Soc., 89 [2] (2006) 494–500

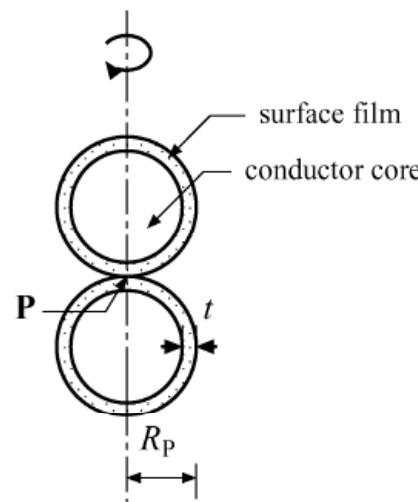


TEMPERATURE GRADIENTS AND DIFFUSION

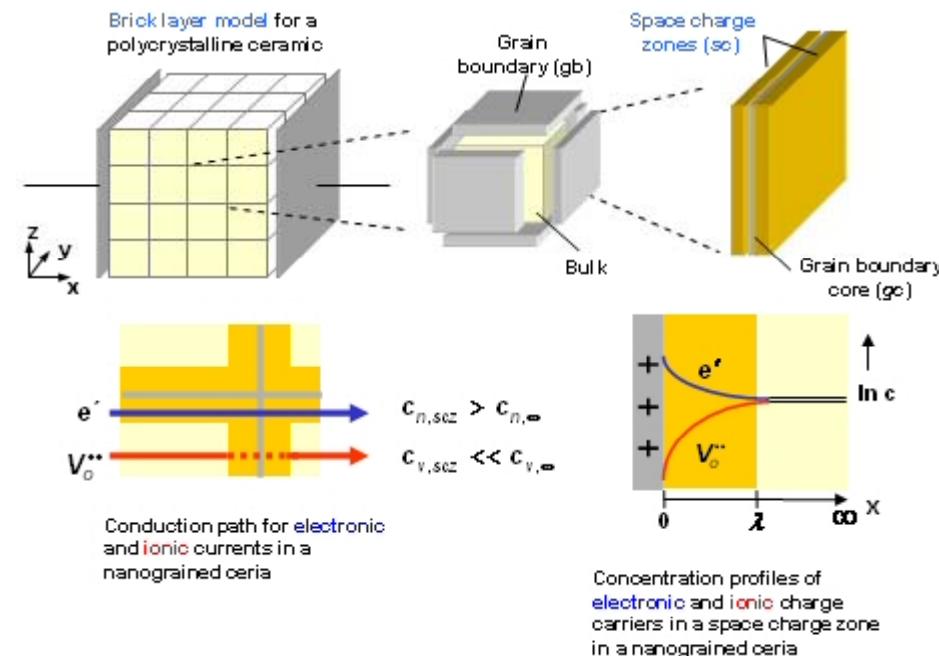


Microscopic temperature gradients – grain boundary resistance

metals



Ionic materials



S. Kim and J. Maier, *J. Electrochem. Soc.*, 149 (10), J73 (2002).



MECHANISMS IN FAST SINTERING

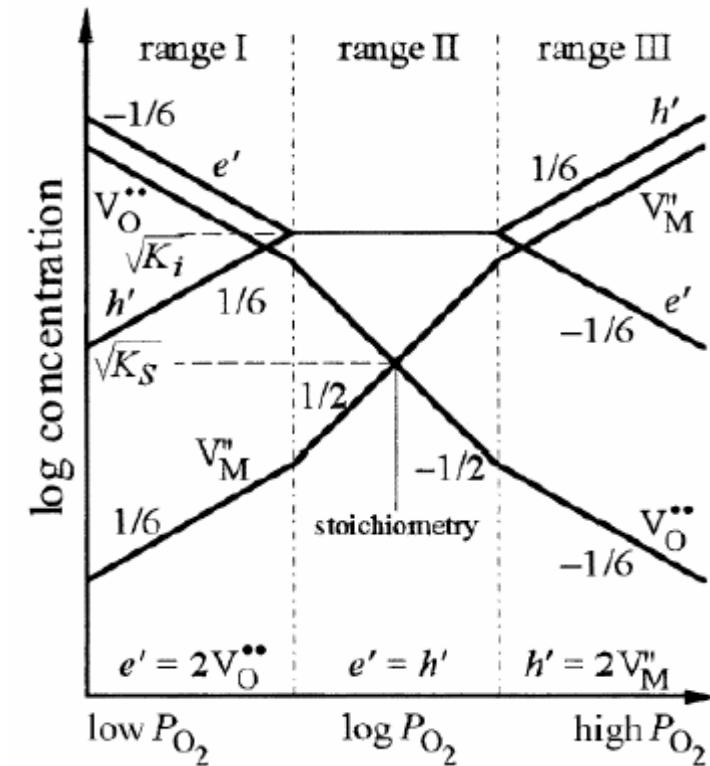
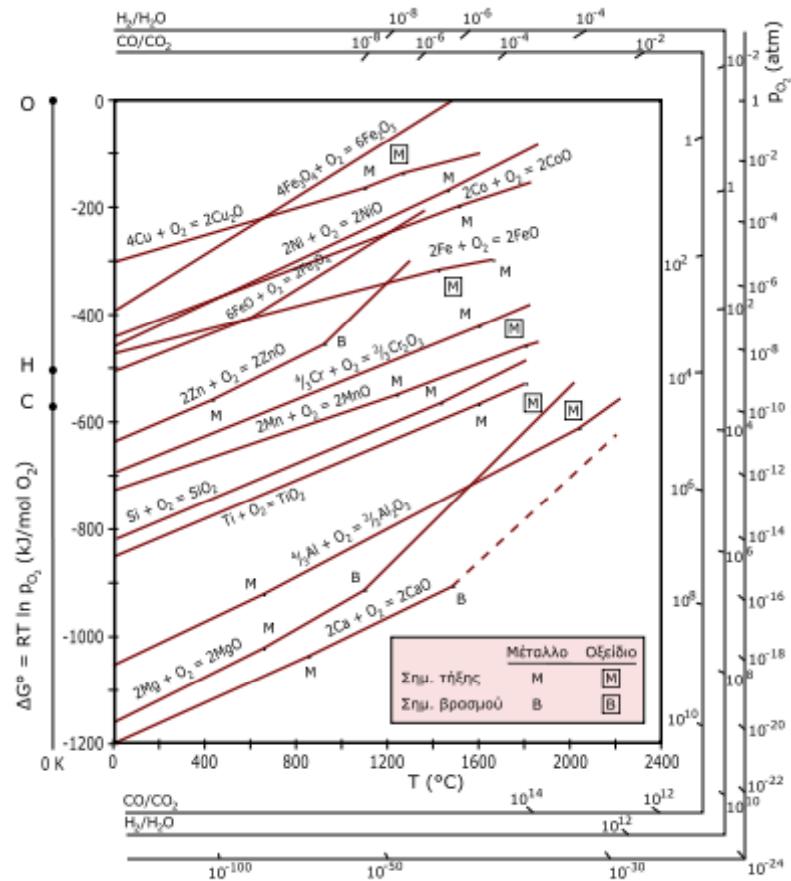


- Arc and spark discharge
- Electromigration
- Electric field induced diffusion
- Temperature gradients
- Pressure and stress gradient
- **Modification of defects concentration**
- Heating rate



MODIFICATION IN DEFECTS CONCENTRATION

FAST environment is strongly reductant
It can produce oxygen substiochiometry or even complete reduction





BASIC MECHANISMS INVOLVED IN FAST SINTERING

Umberto Anselmi-Tamburini

*Department of Chemistry
University of Pavia
Italy*